TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ($L^2-\pi$ -MOSV)

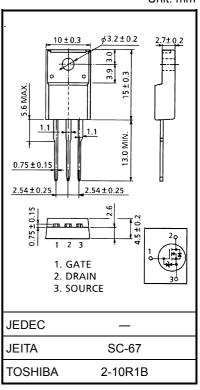
2SK2232

Chopper Regulator, DC–DC Converter and Motor Drive Applications

- 4 V gate drive
- Low drain-source ON resistance $: R_{DS} (ON) = 36 m\Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 16 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 60 \ V)$
- Enhancement-mode : $V_{th} = 0.8 \sim 2.0 V (V_{DS} = 10 V, I_D = 1 mA)$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	60	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V _{DGR}	60	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	25	А	
	Pulse (Note 1)	I _{DP}	100	А	
Drain power dissipatio	n (Tc = 25°C)	PD	35	W	
Single pulse avalanche energy (Note 2)		E _{AS}	156	mJ	
Avalanche current		I _{AR}	25	А	
Repetitive avalanche energy (Note 3)		E _{AR}	3.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch−c)}	3.57	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	62.5	°C / W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 339 μ H, R_G = 25 Ω , I_{AR} = 25 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.

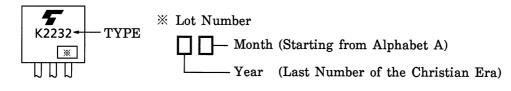
Electrical Characteristics (Ta = 25°C)

Charao	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	irrent	I _{GSS}	V_{GS} = ±16 V, V_{DS} = 0 V	_	_	±10	μA	
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V		_	100	μA	
Drain-source br voltage	eakdown	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	60	-	_	V	
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V	
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 4 V, I _D = 12 A		0.057	0.08	Ω	
			V _{GS} = 10 V, I _D = 12 A	—	0.036	0.046		
Forward transfe	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 12 A	10	16	_	S	
Input capacitance	e	C _{iss}			1000	_	pF	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		200	_		
Output capacitance		C _{oss}			550	_		
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \int I_{D} = 12A$ $V_{GS} \stackrel{0V}{}_{0V} \int I_{D} = 12A$ $R_{L} = 2.5\Omega$ $V_{DD} = 30V$ $Duty \le 1\%, t_{W} = 10\mu s$		20	_		
	Turn-on time	t _{on}		_	30	_	20	
	Fall time	t _f		_	55	_	ns	
	Turn-off time	t _{off}			130	_		
Total gate charge (Gate-source plus gate-drain)		Qg		_	38	_		
Gate-source charge		Q _{gs}	V _{DD} ≈ 48 V, V _{GS} = 10 V, I _D = 25 A		25	_	nC	
Gate-drain ("miller") charge		Q _{gd}			13	_		

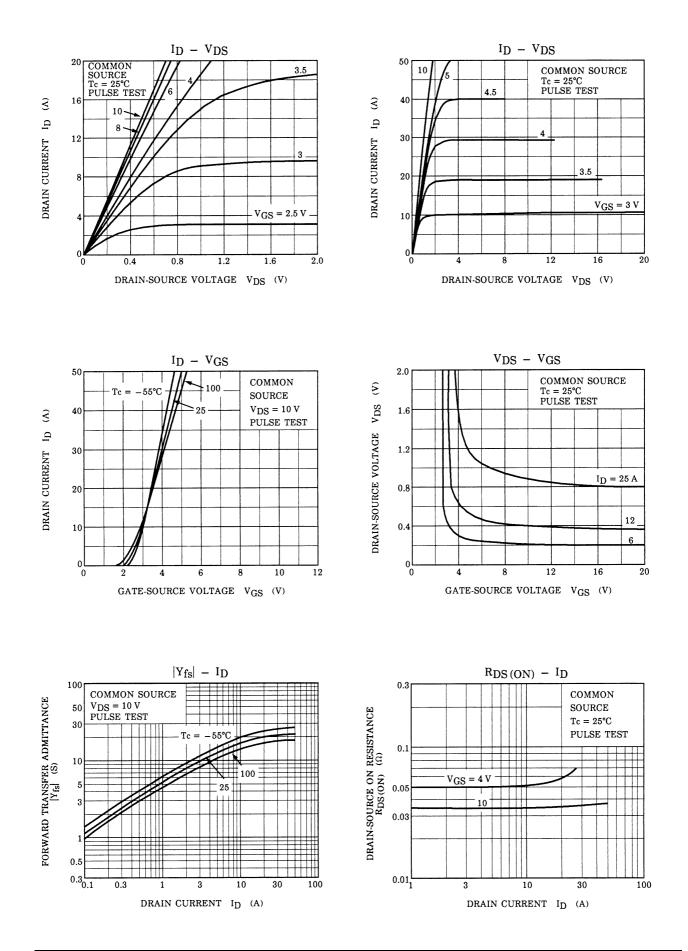
Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	25	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	100	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 25 A, V _{GS} = 0 V	_	_	-1.8	V
Reverse recovery time	t _{rr}	I _{DR} = 25 A, V _{GS} = 0 V, dI _{DR} / dt = 50 A / μs	_	50	_	ns
Reverse recovered charge	Q _{rr}	$1DR = 23 A, VGS = 0 V, UDR / Ut = 30 A / \mus$		35		μC

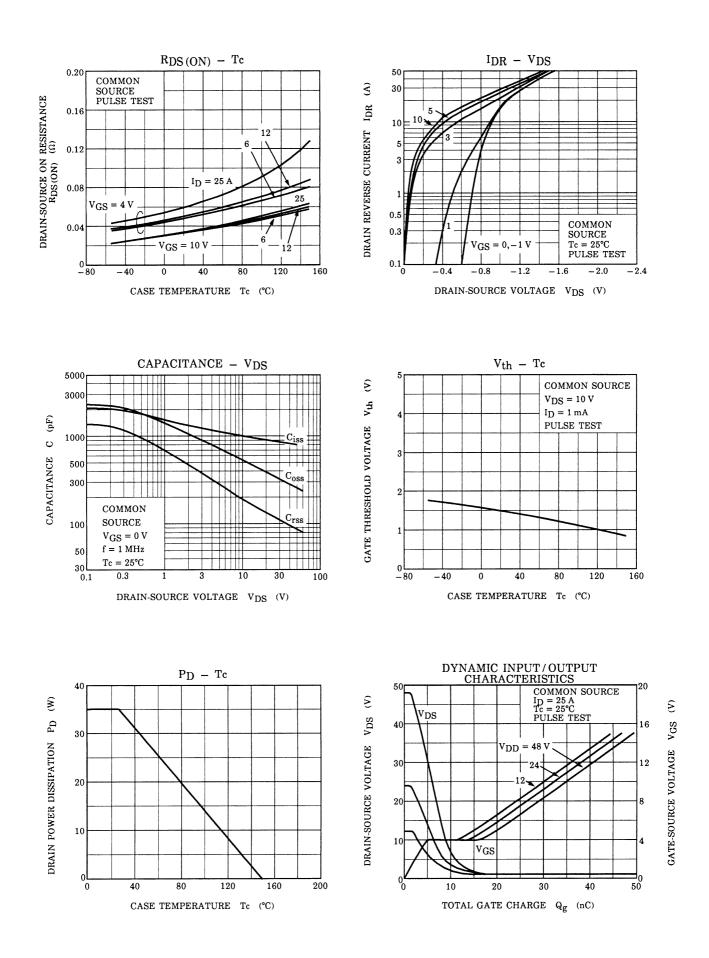
Marking

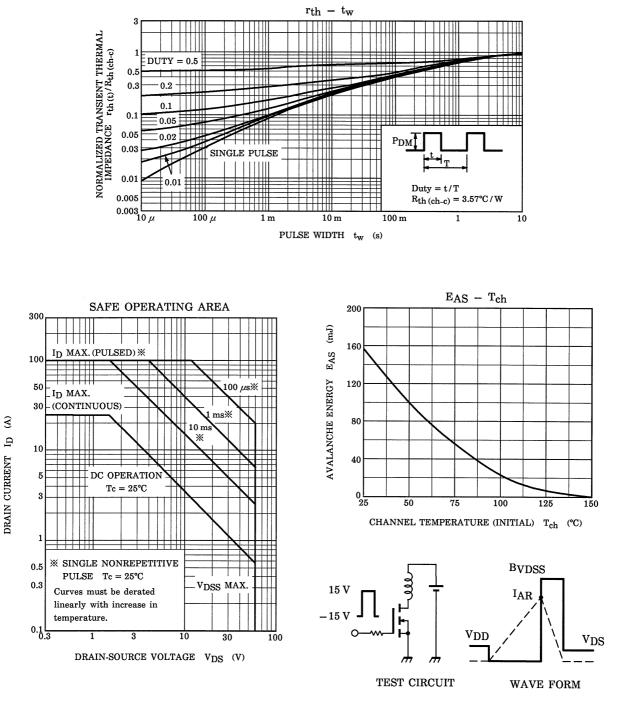


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 $\begin{array}{ll} \mathrm{R}_{\mathrm{G}} = 25 \ \Omega \\ \mathrm{V}_{\mathrm{DD}} = 25 \ \mathrm{V}, \ \mathrm{L} = 339 \ \mathrm{\mu}\mathrm{H} \end{array} \qquad \qquad \mathrm{E}_{\mathrm{AS}} = \frac{1}{2} \cdot \mathrm{L} \cdot \mathrm{I}^2 \cdot \left(\frac{\mathrm{B}_{\mathrm{VDSS}}}{\mathrm{B}_{\mathrm{VDSS}} - \mathrm{V}_{\mathrm{DD}}} \right) \\ \end{array}$

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